

Session TU3D

High Density Microwave Packaging (HDMP) Program

Chairman:

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The ARPA/Tri-Service “High Density Microwave Packaging” (HDMP) program started in late 1993 to develop advanced multi-chip assembly packaging and interconnect technology for next generation airborne and space-based phased array antenna radars. Three dimensional RF interconnect approaches are being developed to realize affordable “tile type” transmit/receive modules. Results of the HDMP Phase 1 programs are presented in this session.

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1:30 p.m.–3:00 p.m., Tuesday, May 16, 1995
Room A3